ABSTRACT OF THE DISCLOSURE

An organopolysiloxane composition for molding purposes is provided which includes: (A) an organopolysiloxane with at least two alkenyl groups bonded to silicon atoms, (B) a straight chain organopolysiloxane with a hydrogen atom bonded to a silicon atom at both terminals, (C) an organohydrogenpolysiloxane with at least three hydrogen atoms bonded to silicon atoms within a single molecule and including a RHSiO unit and a $R_2XSiO_{1/2}$ unit (wherein R is an unsubstituted or a substituted monovalent hydrocarbon group with no alkenyl groups, and X represents either a hydrogen atom or a group represented by R as defined above) within the molecule, (D) a hydrosilylation reaction catalyst, and (E) finely powdered silica, wherein the total number of hydrogen atoms bonded to silicon atoms within the constituent (B) and the constituent (C) ranges from 1 to 5 per alkenyl group within the constituent (A), and the number of hydrogen atoms bonded to silicon atoms within the constituent (B) accounts for 20 to 70 mol% of the combined number of hydrogen atoms bonded to silicon atoms within the constituent (B) and the constituent (C). This composition displays superior mold releasability relative to materials such as urethane resins, epoxy resins, dicyclopentadiene resins and polyester resins, and moreover also displays superior elongation at shearing and tear strength, and can be suitably used as a highly durable mold composition.